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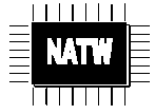
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Call for Papers

27th North Atlantic Test Workshop

May 7-9, 2018

Essex Resort & Spa

Essex, Vermont

<http://natw.ieee.org>

Sponsored by the

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IEEE Region 1

The IEEE North Atlantic Test Workshop provides a forum for discussions on the latest issues relating to high quality, economical, and efficient test methodologies and designs. The 27th NATW will feature a tutorial on Monday on the subject of verification. In addition to traditional topics, the 27th NATW will feature a general theme of “Silicon Photonics.” Major topics can include, but are not limited to:

Analog, Mixed Signal & RF Testing	DFM, Defect Analysis & Defect-Based Testing
Built-In Self-Test (BIST)	Multi-Chip Module Testing
Board and Package Level Testing	Memory & MEMS Testing
Delay & Performance Testing	Nanotechnology Testing
Design Verification/Validation	Online Testing
Diagnosis and Debug	System-on-Chip (SOC) Test & Debug
Fault Modeling/Simulation	Test Quality/System Reliability
FPGA & Embedded Core Testing	Test Resource Partitioning
IDDQ Testing	Testing for Soft Errors/Defects
Machine Learning for Testing	

The Program Committee invites authors to submit original, unpublished papers and panel proposals. Submissions may be in terms of extended summaries or full papers. Detailed instructions for submission can be found at the “*Author Information and Paper Submission*” link <http://natw.ieee.org>.

Papers found suitable for archival publication will be recommended by the program committee for submission to the “Journal of Electronic Testing: Theory and Applications (JETTA),” published by Springer. In addition, publication in IEEE Explorer is an option for authors who choose to do this.

Jake Karrfalt Best Student Paper Award

To encourage student participation in the testing research community, NATW has sessions dedicated to student presentations and includes a Best Student Paper Award.

James Monzel Service Award: The award is issued to individuals for dedicated service to NATW.

Important Dates: Submission – **03/12/2018** / Notification of acceptance – **04/6/2018**
Submission of final papers – **04/25/2018** / Submission of PPT presentations – **05/2/2018**

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